

Variant: 001
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 TID #: PMP4481



PMP4481 REV 1.4 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	IPCB1	1		PMP4481	Any	Printed Circuit Board	
2	C1, C2	2	100uF	C3216X5R1A107M160AC	TDK	CAP, CERM, 100 µF, 10 V, +/- 20%, X5R, 1206 190	1206 190
3	C3	1	47uF	GRM21BR61A476ME15	MuRata	CAP, CERM, 47 µF, 10 V, +/- 20%, X5R, 0805	0805
4	C4, C9, C19, C21	4	0.1uF	GRM155R61C104KA88D	MuRata	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X5R, 0402	0402
5	C6	1	6800pF	GRM155R71E682KA01D	MuRata	CAP, CERM, 6800 pF, 25 V, +/- 10%, X7R, 0402	0402
6	C7	1	680pF	C1005C0G1E681J	TDK	CAP, CERM, 680 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
7	C10	1	330pF	C1005C0G1H331J	TDK	CAP, CERM, 330 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
8	C11, C12, C13, C14, C15	5	47uF	JMK212BJ476MG-T	Taiyo Yuden	CAP, CERM, 47 µF, 6.3 V, +/- 20%, X5R, 0805	0805
9	C17	1	560pF	GRM155C1E561JA01D	MuRata	CAP, CERM, 560 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
10	C18, C20	2	10uF	GRM155R61A106ME11	MuRata	CAP, CERM, 10 µF, 10 V, +/- 20%, X5R, 0402	0402
11	J1, J2	2		ED555/2DS	On-Shore Technology	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm
12	J3, J4	2		1-1634505-0	AMP	Conn Socket BNC straight 50 ohm PCB mount	BNC
13	L1	1	1uH	PCMB053T-1R0MS	Susumu Co Ltd	Inductor, 1 µH, 7 A, 0.014 ohm, SMD	4.15x4mm
14	R1	1	51.1k	CRCW040251K1FKED	Vishay-Dale	RES, 51.1 k, 1%, 0.063 W, 0402	0402
15	R2	1	80.6k	CRCW040280K6FKED	Vishay-Dale	RES, 80.6 k, 1%, 0.063 W, 0402	0402
16	R3	1	61.9k	CRCW040261K9FKED	Vishay-Dale	RES, 61.9 k, 1%, 0.063 W, 0402	0402
17	R4	1	66.5k	CRCW040266K5FKED	Vishay-Dale	RES, 66.5 k, 1%, 0.063 W, 0402	0402
18	R5	1	28.0k	CRCW040228K0FKED	Vishay-Dale	RES, 28.0 k, 1%, 0.063 W, 0402	0402
19	R6	1	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
20	R7	1	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
21	R8	1	51.1	CRCW040251R1FKED	Vishay-Dale	RES, 51.1, 1%, 0.063 W, 0402	0402
22	R9	1	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0, 1%, 0.063 W, 0402	0402
23	R10	1	0	CRCW0402000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
24	TP1, TP2, TP4, TP5	4	Red	5010	Keystone	Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint
25	TP3, TP6	2	Black	5011	Keystone	Test Point, Multipurpose, Black, TH	Black Multipurpose Testpoint
26	U1	1		TPS54678RTER	Texas Instruments	2.95 V to 6 V INPUT, 6 A OUTPUT, 2 MHz, SYNCHRONOUS STEP DOWN SWITCHER WITH INTEGRATED FET (SWIFT?), RTE0016F	RTE0016F
27	C5	0	100uF	APXE160ARA101MF80G	Chemi-Con	CAP, AL, 100 µF, 16 V, +/- 20%, 0.024 ohm, SMD	F80
28	C8	0	91pF	GRM155C1H910JA01D	MuRata	CAP, CERM, 91 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
29	C16	0	560uF	APXF6R3ARA561MH80G	Chemi-Con	CAP, AL, 560 µF, 6.3 V, +/- 20%, 0.009 ohm, SMD	H80
30	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
31	H2, H5, H8, H11	0		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
32	H3, H6, H9, H12	0		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw

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